

FORM PTO-1449

LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)

ATTY. DOCKET NO.

100111595-1

SERIAL NO.

APPLICANT

BASH et al.

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11021 U.S. PTO
10/022112
12/14/01

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

[illegible]

FOREIGN PATENT DOCUMENTS

[illegible]

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

P.?	R. Hannemann, L. R. Fox and M. Mahalingham, "Thermal Design for Microelectronic Components," in "Advances in Cooling Techniques for Computers" 245-276 (Win Aung ed., Hemisphere Publishing Corporation, 1991).
P.?	"Advances in Cooling Techniques for Computers" 150-153 (Win Aung ed., Hemisphere Publishing Corporation, 1991).
P.?	Robert Darveaux and Iwona Turlik, "Backside Cooling of Flip Chip Devices in Multichip Modules," ICMCM Proc. 230-241 (1992).

EXAMINER

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U.S. PATENT DOCUMENTS

[illegible]

FOREIGN PATENT DOCUMENTS

[illegible]

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

P.7	Herman W. Chu, Christian L. Belady and Chandrakant D. Patel, "A Survey of High-performance, High Aspect Ratio, Air Cooled Heat Sinks," International Systems and Packaging Symposium (1999).
P.7	Chandrakant D. Patel, "Backside Cooling Solution for High Power Flip Chip Multi-Chip Modules," IEEE ECTC Proceedings 442-449 (May, 1994).

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